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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/687,096	10/15/2003	James L. Voelz	108298737US	7233
25096	7590	06/02/2006	EXAMINER	
PERKINS COIE LLP PATENT-SEA P.O. BOX 1247 SEATTLE, WA 98111-1247				CRANE, SARA W
		ART UNIT		PAPER NUMBER
		2811		

DATE MAILED: 06/02/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

H-9

Office Action Summary	Application No.	Applicant(s)
	10/687,096	VOELZ, JAMES L.
	Examiner Sara W. Crane	Art Unit 2811

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) Responsive to communication(s) filed on 15 March 2006.
- 2a) This action is FINAL. 2b) This action is non-final.
- 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) Claim(s) 1-38 is/are pending in the application.
 - 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) Claim(s) _____ is/are allowed.
- 6) Claim(s) 1-38 is/are rejected.
- 7) Claim(s) _____ is/are objected to.
- 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) The specification is objected to by the Examiner.
- 10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 - a) All
 - b) Some *
 - c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) Notice of References Cited (PTO-892)
- 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date 3/13/2004, 6/18/2004
- 4) Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____
- 5) Notice of Informal Patent Application (PTO-152)
- 6) Other: _____

DETAILED ACTION

Claim Rejections - 35 USC § 103

Claims 1-38 are rejected under 35 U.S.C. 103(a) as being unpatentable over Farnworth et al. (6,368,896) in view of Weber (6,560,122).

With respect to claim 1, figure 2A of Farnworth et al. shows a plurality of dies 32 at an active side of wafer 30, where the dies have integrated circuits connected to bond pads (figure 4, for example). A redistribution assembly (flex circuit 34) is formed on the wafer, as shown by figure 2B. The flex circuit includes conductive traces and dielectric tape (column 4, lines 33-40), and is bonded to (or "deposited on") the dies. Next, the dies can be singulated by cutting or shearing the wafer (column 4, lines 40-44). Weber teaches to package chips by using backside molding material, which is flowable until cured (column 7, lines 21-25). It would have been obvious to package the singulated dies of Farnworth et al. as taught by Weber, in order to protect the backside from damage and to provide for packaging as is usual in the art.

With respect to claim 2, Farnworth shows in the cover figure that solder balls 54 are attached to pads 48, and film 36 would have a protective function. With respect to claims 3-6, each of these methods are known in the art for the purpose of applying semiconductor polymeric packaging material, and would have been obvious to obtain known advantages of each method. A molding material of epoxy, as in claim 25, would have been obvious, because this is probably the most commonly used material for semiconductor packaging, and the specific processing temperatures and times of claims 20-24 would depend on the type of epoxy or other molding compound used, because

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optimization of processing temperature and time for molding material is always needed.

The rest of the claims have the same limitations as those discussed above, and would have been obvious for the same reasons.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to S. Crane, whose telephone number is (571) 272-1652.

The supervisor for Art Unit 2811, Eddie Lee can be reached on (571) 272-1732. The fax phone number for the organization where this application or proceeding is assigned is (571) 273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



Sara W. Crane
Primary Examiner
Art Unit 2811